



**BGA Rework Stations**  
**Model: IR860-II**

## SMD / BGA Rework Station

Features:

1. Compact design, light weight soldering iron and hot air blower meet various soldering demands and remove kinds of chips in repair work.
2. Best products and factory price.
3. Time delivery and the shortest delivery time.
4. Advanced infrared BGA rework station.
5. With independent preheating function , which can let you preheat pcb boards or bga chips before soldering.
6. Large power and rapid heating. Temperature can be conveniently adjusted and the temperature is accurate and stable, and not affected by airflow.
7. Stepless airflow adjusting with a wide range. Temperature can be conveniently adjusted.
8. Sensitive electromagnetic inductor in handle ensures the unit beginning working immediately so long as the handle is held. When handle is put on the holder, the system will return back to standby mode. Easy to use.

Application:

Work great for soldering/desoldering surface mount components in the circuit board of mobile phone. Suitable for heating shrink, drying, lacquer removal, viscosity removal, ice-out, pre-heating and glue soldering.

Specifications for IR860			
Solderlight Control		Pre-heater	
Power Rating	220-240Vac 50 hz	Power Rating	230 vac
Fuse	T2A (Slow Type)	Fuse (Delay type)	T 5 A
Output	15Vac 150W	Output	1300W
IR Lamp Temp. range	45°-450° Celsius (113°-842° Fahrenheit)	Temperature range	30°-350° Celsius (86°-662° Fahrenheit)
Time settings	0-900sec	Time settings	0-900sec
Size (W*H*D)	170 x 100 x 200mm (6.7" x 3.94" x 7.9")	Size (W*H*D)	402 x 90 x 260mm (11" x 3.5" x 10")
Net weight	7.25 lbs	Net weight	12.81 KGS